



# SOT1458-1

plastic dual in-line compatible thermal enhanced super thin quad flat package; no leads; 14 terminals; body 1.5 x 2.1 x 0.32 mm

26 April 2016

Package information

## 1. Package summary

|                                |                               |
|--------------------------------|-------------------------------|
| Terminal position code         | B (bottom)                    |
| Package type descriptive code  | DHX2QFN                       |
| Package type industry code     | DHX2QFN14                     |
| Package style descriptive code | TQFP (thin quad flat package) |
| Package style suffix code      | NA (not applicable)           |
| Package body material type     | P (plastic)                   |
| Mounting method type           | S (surface mount)             |
| Issue date                     | 10-11-2015                    |

Table 1. Package summary

| Symbol         | Parameter                      |  | Min  | Typ | Nom  | Max  | Unit |
|----------------|--------------------------------|--|------|-----|------|------|------|
| D              | package length                 |  | 2.05 | -   | 2.1  | 2.15 | mm   |
| E              | package width                  |  | 1.45 | -   | 1.5  | 1.55 | mm   |
| A              | seated height                  |  | 0.3  | -   | 0.32 | 0.33 | mm   |
| e              | nominal pitch                  |  | -    | -   | 0.4  | -    | mm   |
| n <sub>2</sub> | actual quantity of termination |  | -    | -   | 14   | -    |      |



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2. Package outline

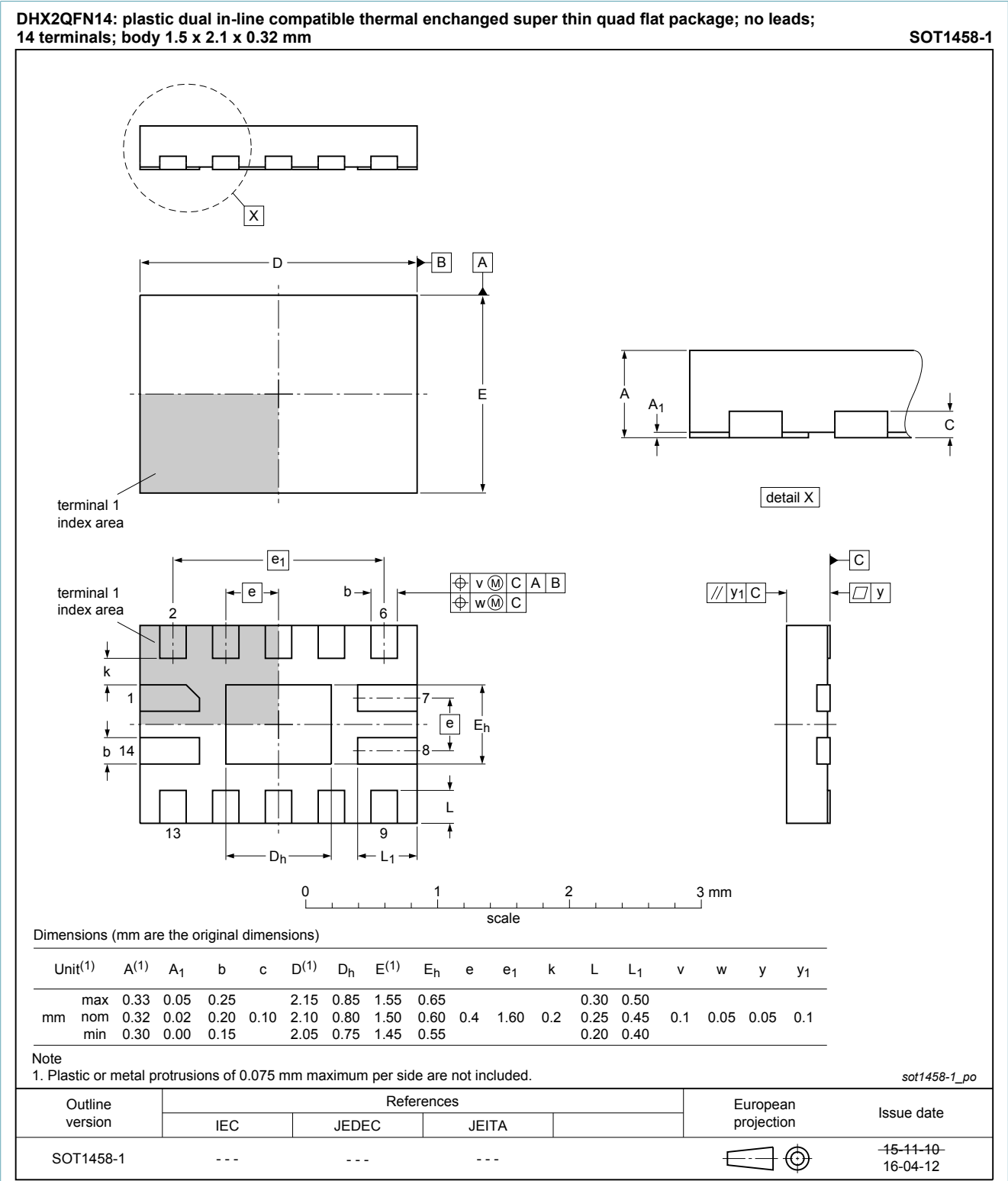
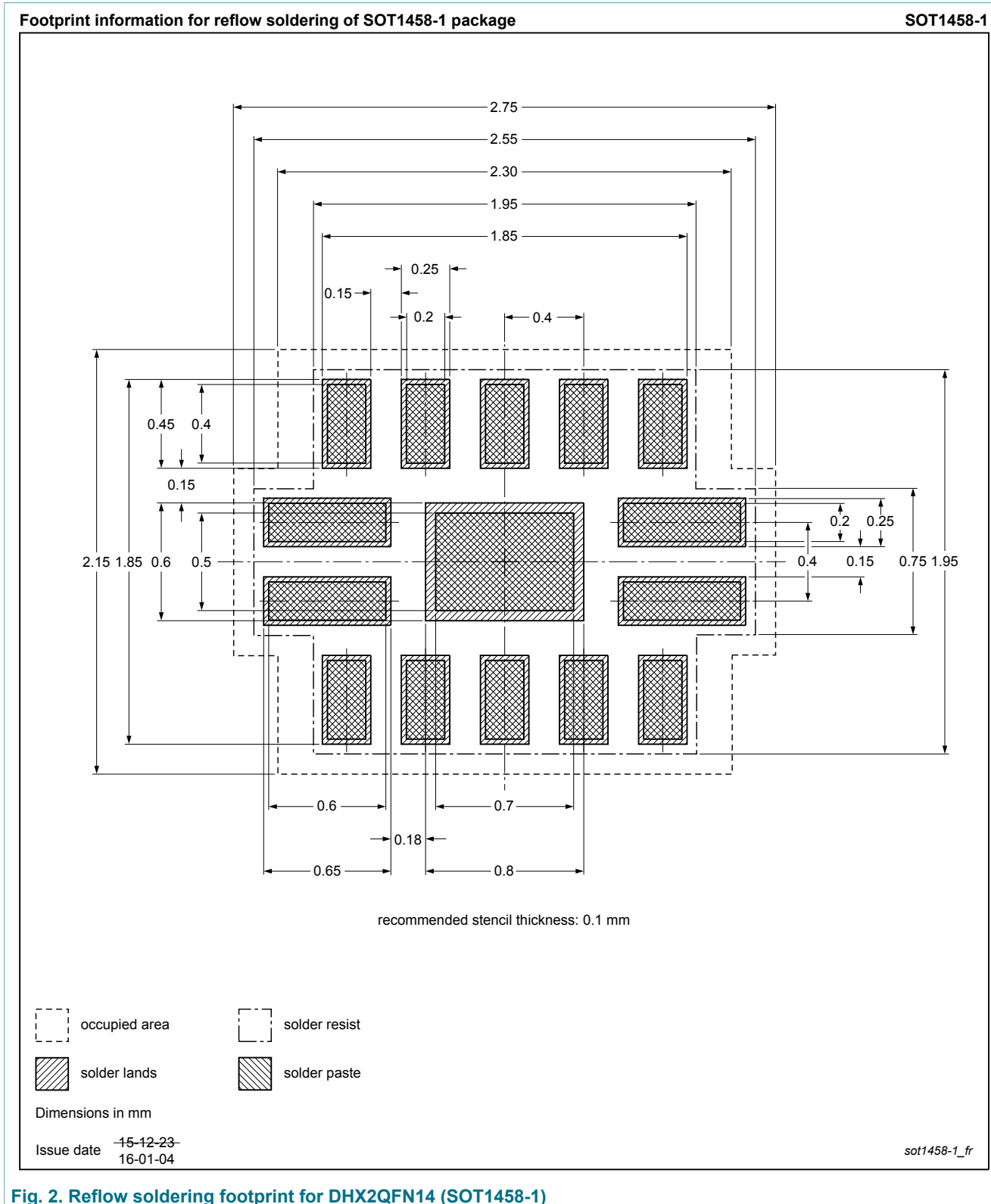


Fig. 1. Package outline DHX2QFN14 (SOT1458-1)

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### 3. Soldering



**Fig. 2. Reflow soldering footprint for DHX2QFN14 (SOT1458-1)**

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## 4. Legal information

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